

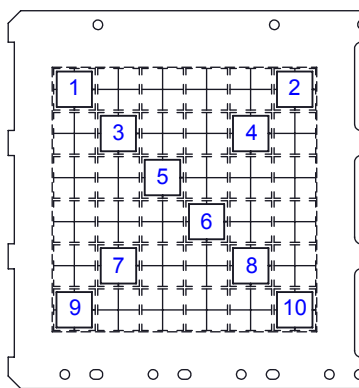
WIRE BONDING QFN48 KIT

KIT BOM (MATERIALS)

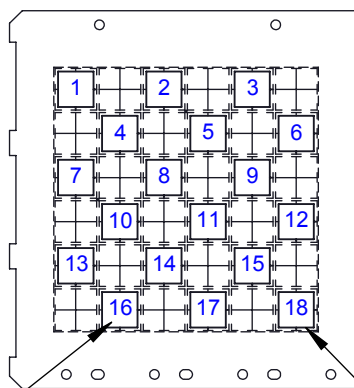
KIT ORDER NBR	QTY DIE	DIE DWG	DESCRIPTION
955401	10	154024	DAISY CHAIN DIE 4.0 x 4.0mm AND QFN48 Cu LEAD FRAME
955402	18		
955403	36		
955101	10	154001	FULLY ALUMINIZED DIE 4.0 x 4.0mm AND QFN48 Cu LEAD FRAME
955102	18		
955103	36		

NOTE: OTHER CONFIGURATION AVAILABLE

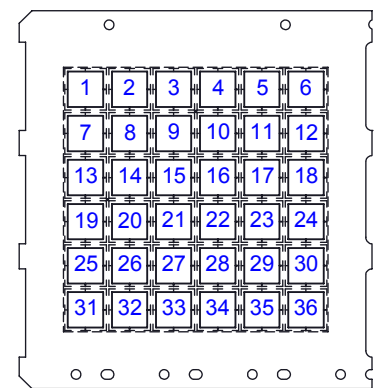
DIE PLACEMENT ON QFN48 LEAD FRAME



10 DIE PER KIT

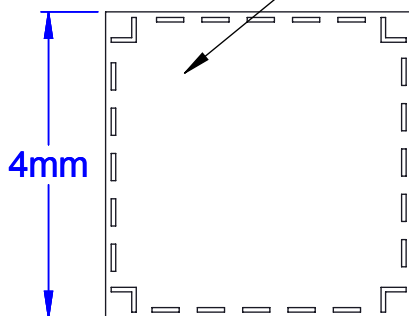


18 DIE PER KIT



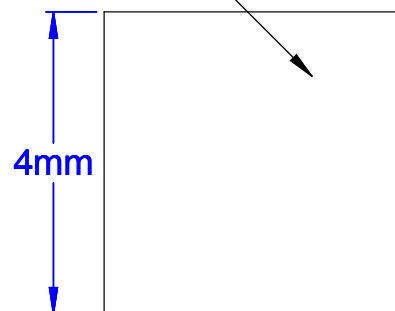
36 DIE PER KIT

DETAIL "A"



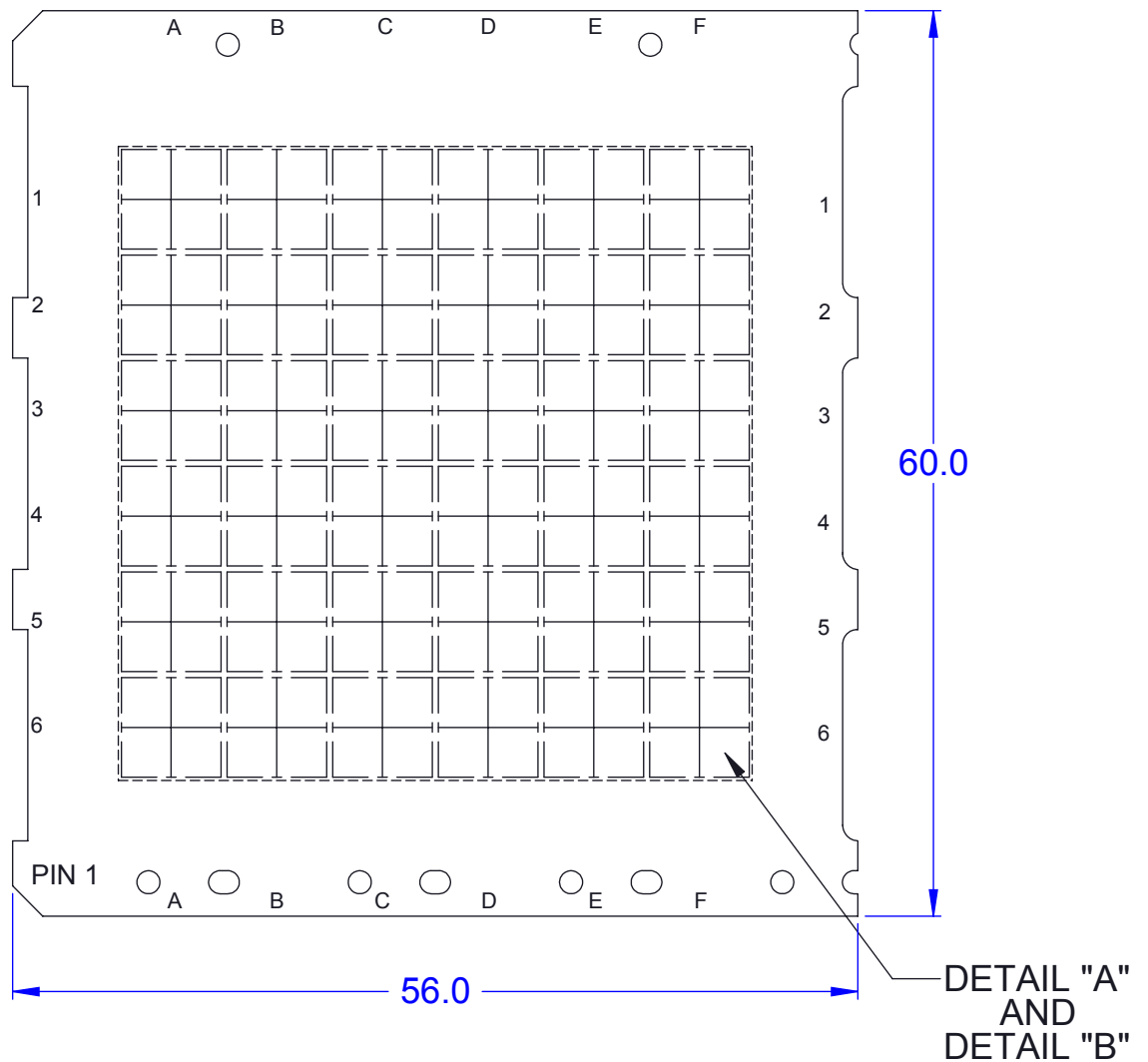
DIE 4x4mm
DWG 154024
DAISY CHAIN

DETAIL "B"



DIE 4x4mm
DWG 154001
FULL AI

APPROVALS	DATE				
DRAWN T. Au	07/30/12				
ENG M. Hart	07/30/12	TITLE QFN48 DIE KIT WIRE BONDING PRACTICE			
MFG					
QA		SCALE	SIZE A	DRAWING NO. 955000	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 6

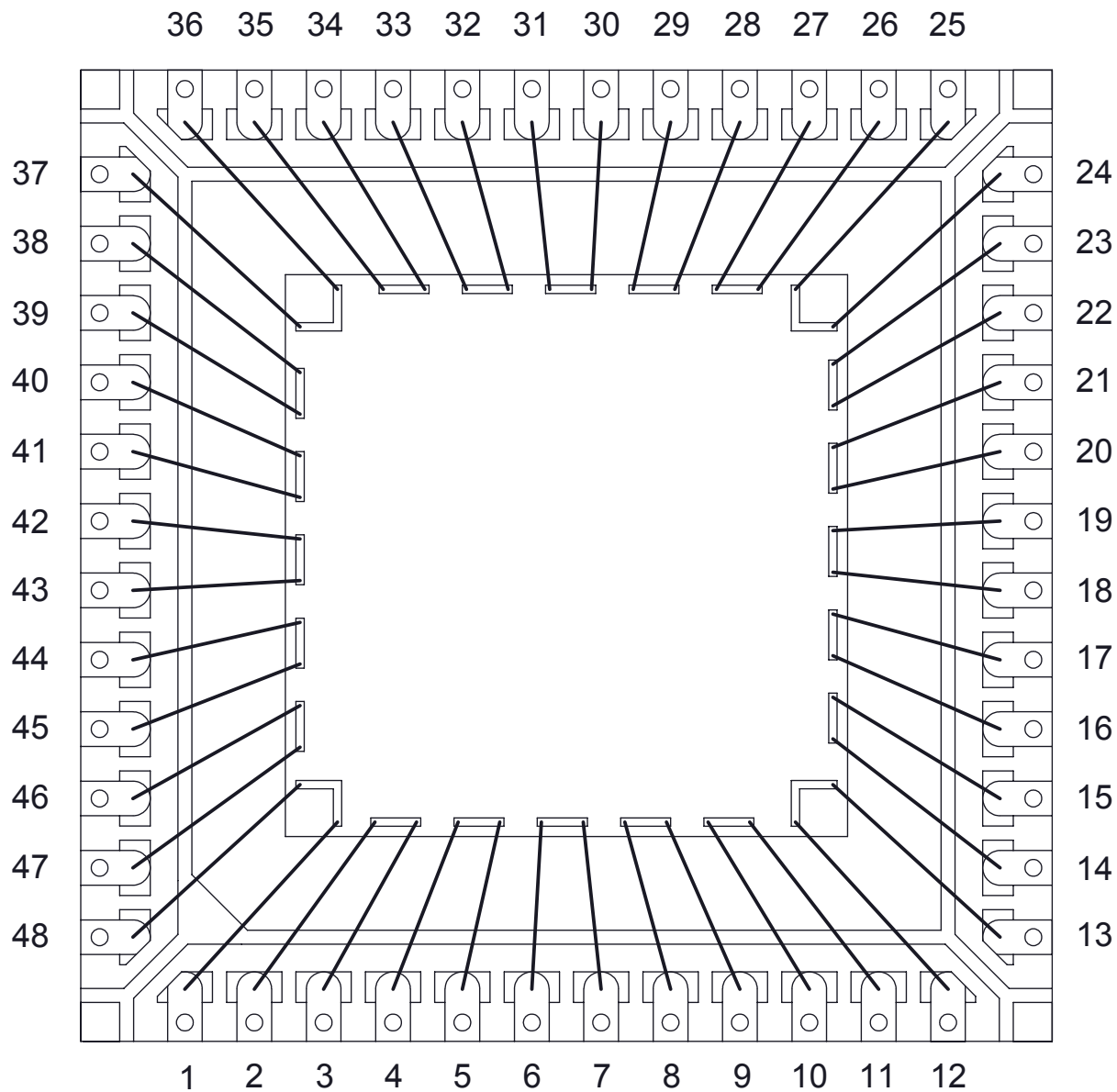


Notes:

1. DIMENSIONS in MM.
2. LEAD FRAME QFN 48 PINS 0.5MM PITCH.
3. DIE BONDING 36X SITES FOR DIE 4x4MM.
4. MATERIAL Cu OLIN 194 F/H.
5. LEAD FRAME THICKNESS 0.203MM.
6. PLATING: NiPdAu.
7. KAPTON TAPE APPLIED TO BOTTOM OF LEAD FRAME.

APPROVALS		DATE				
DRAWN T. Au		07/30/12				
ENG M. Hart		07/30/12	TITLE LEAD FRAME QFN 48 LEAD			
MFG						
QA			SCALE	SIZE A	DRAWING NO. 955001	REV A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 2 OF 6

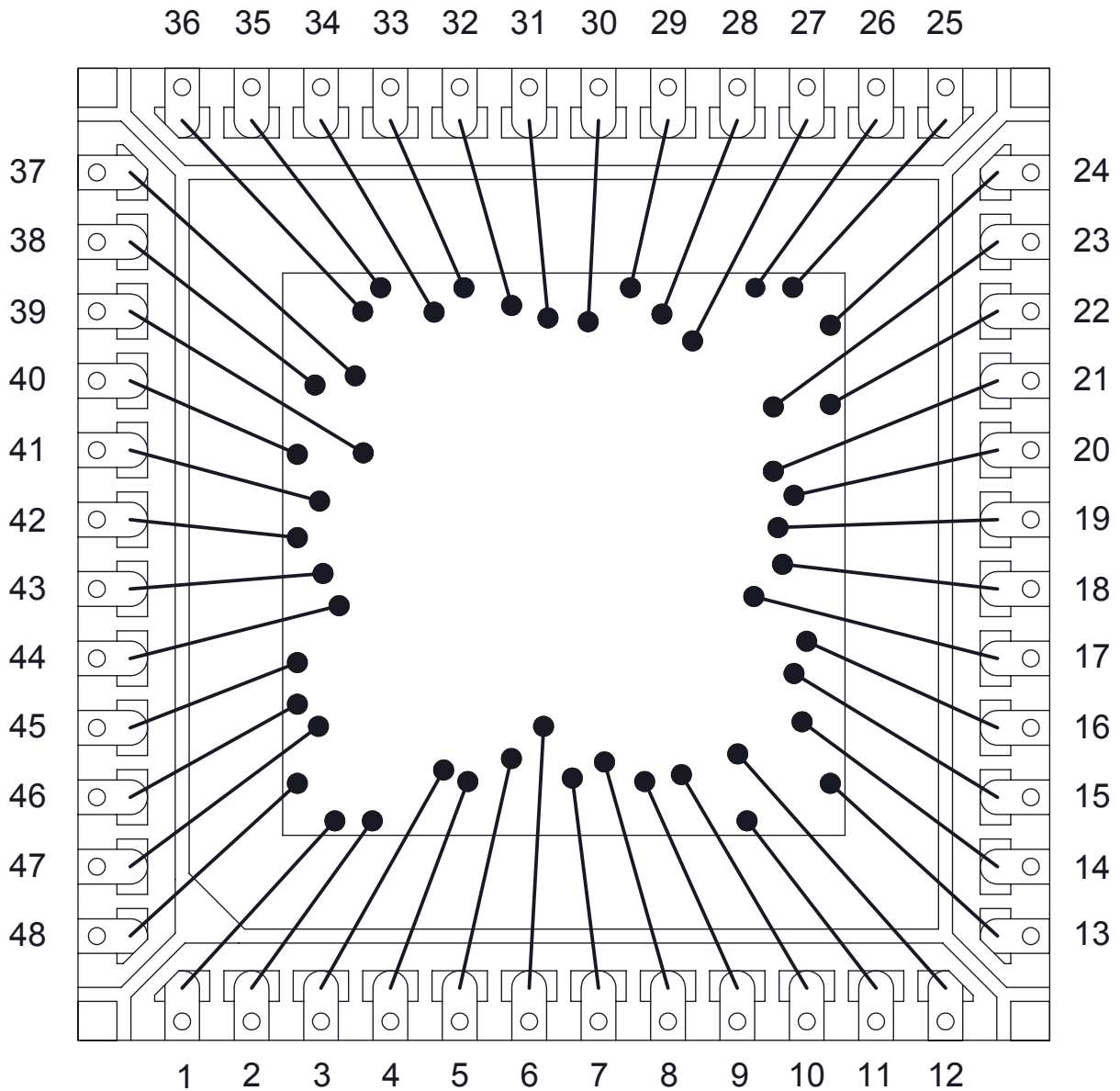
QFN48 LEAD FRAME DETAIL "A"
AFTER WIRE BONDING
DAISY CHAIN DIE



Notes:
1. SCALE 20:1

APPROVALS	DATE				
DRAWN T. Au	07/30/12				
ENG M. Hart	07/30/12	TITLE LEAD FRAME QFN 48 LEAD			
MFG					
QA		SCALE	SIZE A	DRAWING NO. 955002	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 3 OF 6

QFN48 LEAD FRAME DETAIL "B" **AFTER WIRE BONDING** **FULLY ALUMINIZED DIE**

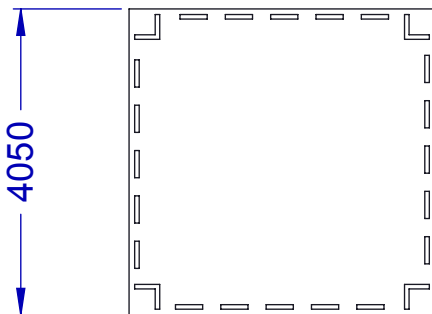
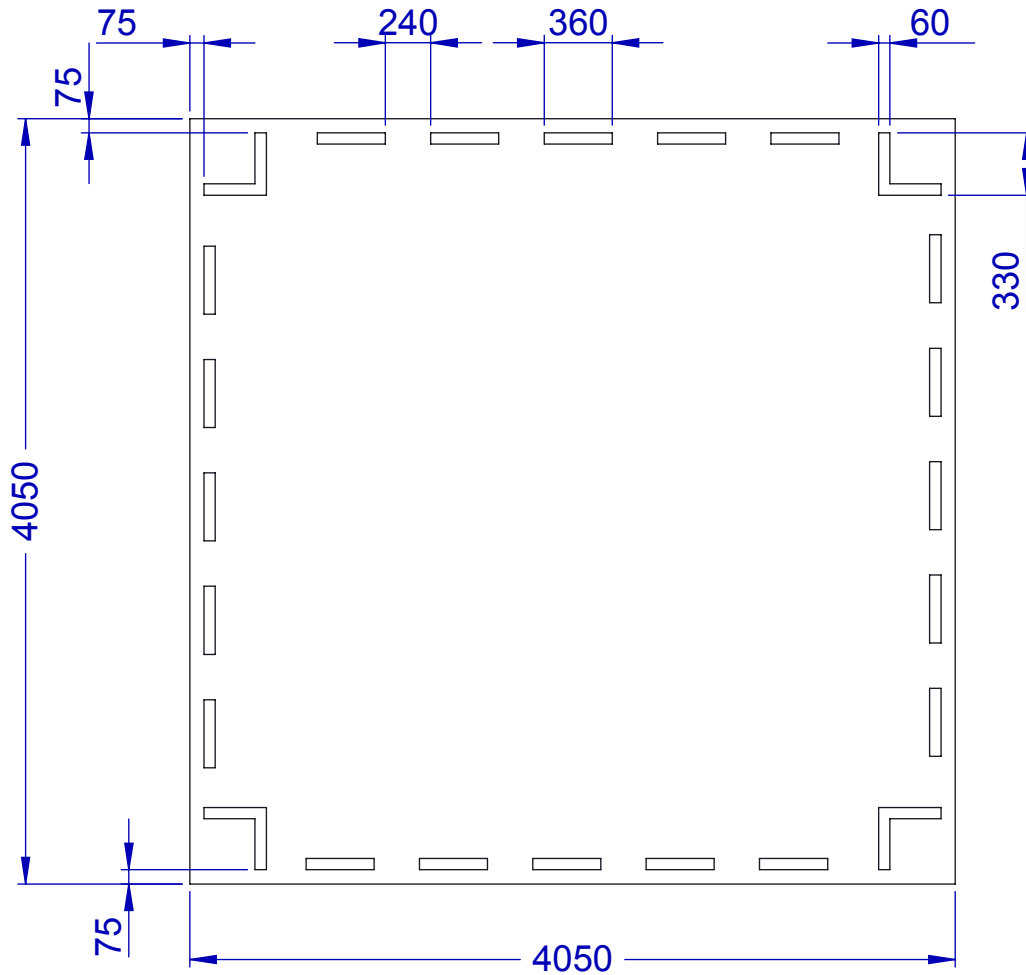


Notes:

1. SCALE 20:1

APPROVALS	DATE	TopLine®			
DRAWN T. Au	07/30/12	TITLE LEAD FRAME QFN 48 LEAD			
ENG M. Hart	07/30/12				
MFG					
QA		SCALE	SIZE A	DRAWING NO. 955002	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 4 OF 6

DAISY CHAIN DIE



SCALE 10:1

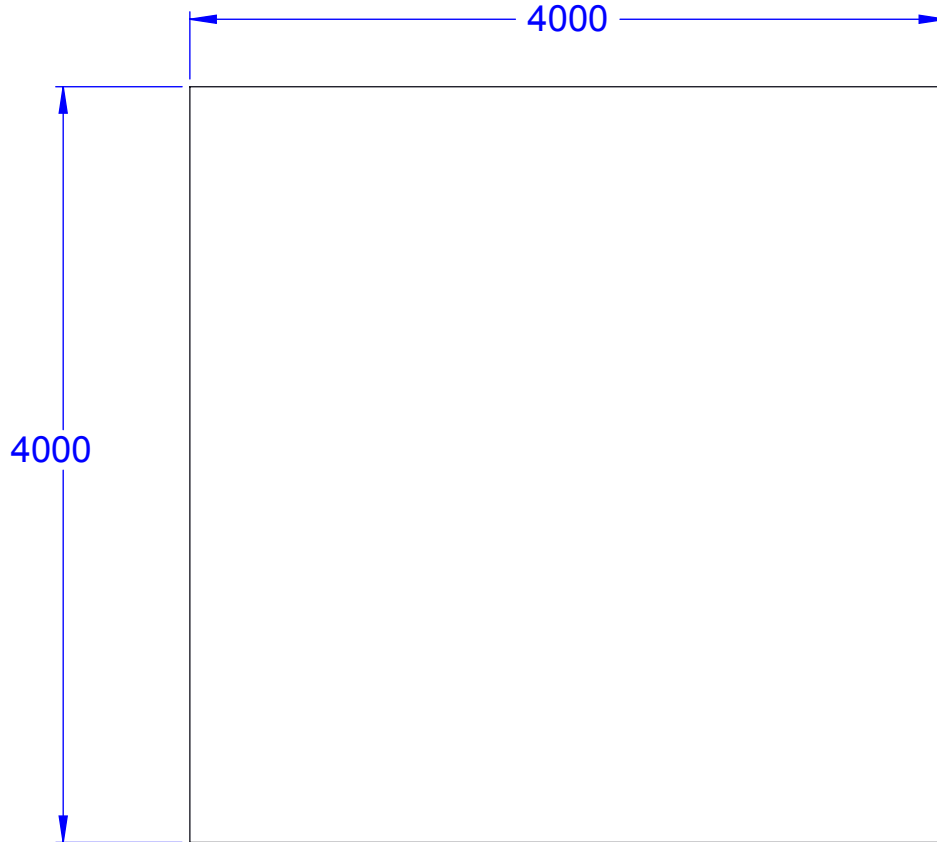
DIMENSIONS IN MICRONS
1.0 mm = 1000um

Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250um ~ 725um.
3. METALLIZATION 1.0 um ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

APPROVALS	DATE				
DRAWN T. Au	07/30/12				
ENG M. Hart	07/30/12	TITLE DAISY CHAIN TEST DIE TD24 4X4MM			
MFG					
QA		SCALE	SIZE	DRAWING NO.	REV
CUST			A	154024	A
REVISED		DO NOT SCALE DRAWING			SHEET 5 OF 6

FULLY ALUMINIZED DIE



Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250um ~ 750um.
3. METALLIZATION 1.0 um ALUMINUM (Al)
OVER 0.75 um SiQ.
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au).
6. FULLY METALLIZED OVER ENTIRE SURFACE OF DIE.



SCALE 6:1

DIMENSIONS IN MICRONS
1.0 mm = 1000um

APPROVALS	DATE				
DRAWN T. Au	07/30/12				
ENG M. Hart	07/30/12	TITLE FULLY ALUMINIZED WIRE BONDABLE DIE			
MFG					
QA		SCALE	SIZE	DRAWING NO.	REV
CUST			A	154001	A
REVISED		DO NOT SCALE DRAWING			SHEET 6 OF 6